

PATENT
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The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. – 18. (Cancelled)

19. (New) An IC chip comprising at least one externally and selectively cuttable member having at least one cuttable section, the cuttable member including a multiplicity of cuttable points, wherein said cuttable member remain cut open so long as at least one cuttable point remains cut open, and wherein

said cuttable member includes a multiplicity of cuttable sections which are coupled at one ends thereof with the same electric potential and coupled at the other ends thereof with respective logic circuits.

20. (New) The IC chip according to claim 19, wherein said cuttable sections have a linear portion of a uniform width.

21. (New) The IC chip according to claim 19, wherein each of said cuttable sections has a narrow portion formed between two wide portions.

22. (New) A semiconductor device, comprising:
an IC chip having

at least one externally and selectively cut member including at least one cut section, the cut member including a multiplicity of cut points, said cut member working normally when at least one of said cut points remains cut open, and

bumps formed on the same side of the IC chip as the cut member in association with respective cut points;

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a substrate/another IC chip; and
a connection member made of an anisotropic conductor and
sandwiched between said IC chip and said substrate/another IC chip, wherein
said IC chip and said substrate/another IC chip are pressed together,
and wherein

 said cut member includes a multiplicity of cut sections which are
coupled at one ends thereof with the same electric potential and coupled at the
other ends thereof with respective logic circuits.

23. (New). The semiconductor device according to claim 22 wherein
said cut sections have a linear portion of a uniform width.

24. (New). The semiconductor device according to claim 22 wherein
each of said cut sections has a narrow portion between two wide portions.